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(54) Title: INSPECTION METHOD FOR DETECTING A DEFECTIVE BONDING INTERFACE IN A SAMPLE SUBSTRATE,
AND MEASUREMENT SYSTEM IMPLEMENTING THE METHOD

[Fig. 3]

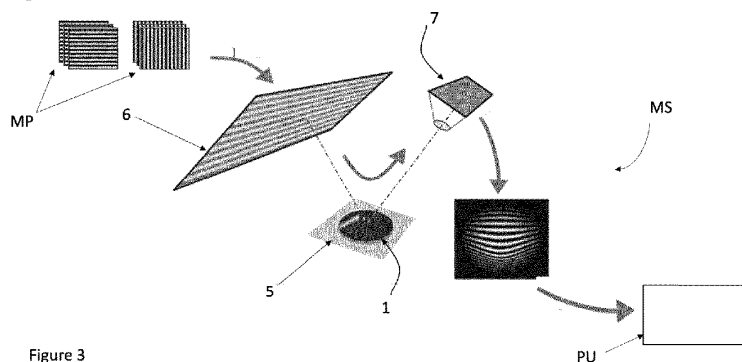


Figure 3

(57) Abstract: The invention concerns a measurement system (MS) and an inspection method for detecting a defective bonding interface in a sample substrate (1) comprising at least one element (3) disposed on a support (2). According to the invention, the method comprising: a providing step (S1) of placing the sample substrate (1) in the measurement system (MS), a measuring step (S2) of establishing an inclination map of the exposed surface (1a), an analyzing step (S3) of the inclination map for identifying a zone or zones of the exposed surface whose inclinations deviate by more than a given threshold from the inclination of the reference surface; and a decision step (S4) of detecting the presence of a defective bond between the element (3) and the support (2), depending on the result of the analyzing step (S3).



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